Smart COM HPC Mini — Compact Edge AI Unleashed

SOM-M250

ADVANTECH × **intel.**

COM HPC Mini Module Powered by Intel® Core™ Ultra Series 3 Processor

SOM-M250 is a compact yet powerful COM module. Equipped with the Intel® Core™ Ultra Series 3 processor, it supports up to 16 cores in a 95×70 mm form factor, minimizing end-product dimensions. It also features a native NPU for AI and flexible I/O, including PCIe Gen5, delivering maximum adaptability for diverse Edge AI applications. SOM-M250 further supports USB4, USB3, dual LAN, and MIPI-CSI to address a wide range of usage scenarios.

With LPDDR5x memory-down and on-board NVMe SSD, SOM-M250 is rugged enough to withstand harsh conditions. In addition, it supports wide temperature ranges (-40 to 85°C), wide voltage input, and AS9100 compliance, making SOM-M250 one of the most reliable COM modules on the market. With Advantech's design-in service, customers can easily achieve faster time-to-market and quickly adopt next-generation Edge AI solutions.

Key Features

High Throughput	Flexible & Scalable	Rugged & Robust	Wide Temp & Voltage

Intel Products & Technology

Series 3 intel CORE ULTRA

intel ARC GRAPHICS

Intel® Core™ Ultra Processors

Intel® Arc™ Graphics

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